ABSTRACT OF THE DISCLOSURE

RESIN-ENCAPSULATION APPARATUS AND MANUFACTURING METHOD OF RESIN-ENCAPSULATED ELECTRONIC COMPONENT

[Problem to be Solved]

To appropriately preheat an unencapsulated substrate that is arranged on a molding die for resin-encapsulation.

[Solution]

A resin-encapsulation apparatus 1 for performing resin-encapsulation of a chip mounted on an unencapsulated substrate 5 comprises molding modules 3A to 3D, lower dies 10 provided on the respective molding modules 3A to 3D, upper dies provided so as to face the respective lower dies 10, cavities 11 to be filled with a flowable resin and provided on the respective lower dies 10, a first carrying means 9 carrying the unencapsulated substrate 5 to each of the molding modules 3A to 3D, a first heater provided on the first carrying means 9, a second carrying means 13 transferring the unencapsulated substrate 5 received from the first carrying means 9 so as to be placed above the cavity 11 and delivering the unencapsulated substrate 5 to a die surface of the upper die, and a second heater provided on the second carrying means 13. The first heater planarly heats the unencapsulated substrate 5 during the process of carrying the unencapsulated substrate 5 to each of the molding modules 3A to 3D. The second heater planarly heats the received unencapsulated substrate 5 until the unencapsulated substrate 5 is delivered to the die surface of the upper die.

Fig. 1